

IMPROVED VIA ADHESION IN MULTILAYER MEMS STRUCTURE

5 ABSTRACT OF THE DISCLOSURE

A method of fabricating improved vias in a multilayer MEMS device. Via seats are patterned into first layer, such that each via will have a via seat at the bottom of the via opening. The via openings are then
10 patterned into a second layer. A third layer of material is deposited, such that the material at least partly fills the via opening and the via seat. The material forms a support post that is anchored to the first layer by means of the material in the via seat.

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